

6367254 MOTOROLA SC (XSTRS/R F)

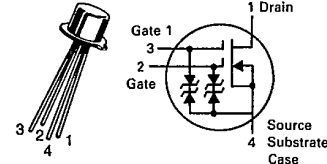
96D 82620 D  
T-31-25

**MAXIMUM RATINGS**

Rating	Symbol	3N211 3N212	3N213	Unit
Drain-Source Voltage	V <sub>DS</sub>	27	35	Vdc
Drain-Gate Voltage	V <sub>DG1</sub> V <sub>DG2</sub>	35 35	40 40	Vdc
Drain Current	I <sub>D</sub>	50		mAdc
Gate Current	I <sub>G1</sub> I <sub>G2</sub>	±10 ±10		mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	360 2.4		mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.2 8.0		Watt mW/°C
Lead Temperature, 1/16" From Seated Surface for 10 seconds	T <sub>L</sub>	300		°C
Junction Temperature Range	T <sub>J</sub>	-65 to +175		°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +175		°C

**3N211  
3N212  
3N213**

**CASE 20-03, STYLE 9  
TO-72 (TO-206AF)**



**DUAL-GATE MOSFET  
VHF AMPLIFIER**

**N-CHANNEL — DEPLETION**

Refer to MPF211 for graphs.

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**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted.)**

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Drain-Source Breakdown Voltage(1) (I <sub>D</sub> = 10 μAdc, V <sub>G1S</sub> = V <sub>G2S</sub> = -4.0 Vdc)	V <sub>(BR)DSX</sub>	25 30	—	Vdc
Instantaneous Drain-Source Breakdown Voltage) (I <sub>D</sub> = 10 μAdc, V <sub>G1S</sub> = V <sub>G2S</sub> = -4.0 Vdc)	V <sub>(BR)DSX</sub>	27 35	—	Vdc
Gate 1-Source Breakdown Voltage(2) (I <sub>G1</sub> = ±10 mAdc, V <sub>G2S</sub> = V <sub>DS</sub> = 0)	V <sub>(BR)G1SO</sub>	±6.0	—	Vdc
Gate 2-Source Breakdown Voltage(2) (I <sub>G2</sub> = ±10 mAdc, V <sub>G1S</sub> = V <sub>DS</sub> = 0)	V <sub>(BR)G2SO</sub>	±6.0	—	Vdc
Gate 1 Leakage Current (V <sub>G1S</sub> = ±5.0 Vdc, V <sub>G2S</sub> = V <sub>DS</sub> = 0) (V <sub>G1S</sub> = -5.0 Vdc, V <sub>G2S</sub> = V <sub>DS</sub> = 0, T <sub>A</sub> = 150°C)	I <sub>G1SS</sub>	—	±10 -10	nAdc μAdc
Gate 2 Leakage Current (V <sub>G2S</sub> = ±5.0 Vdc, V <sub>G1S</sub> = V <sub>DS</sub> = 0) (V <sub>G2S</sub> = -5.0 Vdc, V <sub>G1S</sub> = V <sub>DS</sub> = 0, T <sub>A</sub> = 150°C)	I <sub>G2SS</sub>	—	±10 -10	nAdc μAdc
Gate 1 to Source Cutoff Voltage (V <sub>DS</sub> = 15 Vdc, V <sub>G2S</sub> = 4.0 Vdc, I <sub>D</sub> = 20 μAdc)	V <sub>G1S(off)</sub>	-0.5 -0.5	-6.5 -4.0	Vdc
Gate 2 to Source Cutoff Voltage (V <sub>DS</sub> = 15 Vdc, V <sub>G1S</sub> = 0, I <sub>D</sub> = 20 μAdc)	V <sub>G2S(off)</sub>	-0.2 -0.2	-2.5 -4.0	Vdc
<b>ON CHARACTERISTICS</b>				
Zero-Gate-Voltage Drain Current(3) (V <sub>DS</sub> = 15 Vdc, V <sub>G1S</sub> = 0, V <sub>G2S</sub> = 4.0 Vdc)	I <sub>DSS</sub>	6.0	40	mAdc
<b>SMALL-SIGNAL CHARACTERISTICS</b>				
Forward Transfer Admittance(4) (V <sub>DS</sub> = 15 Vdc, V <sub>G2S</sub> = 4.0 Vdc, V <sub>G1S</sub> = 0, f = 1.0 kHz)	y <sub>fs</sub>	17 15	40 35	mmhos
Reverse Transfer Capacitance (V <sub>DS</sub> = 15 Vdc, V <sub>G2S</sub> = 4.0 Vdc, I <sub>D</sub> = 1.0 mAdc, f = 1.0 MHz)	C <sub>rss</sub>	0.005	0.05	pF
<b>FUNCTIONAL CHARACTERISTICS</b>				
Noise Figure (V <sub>DD</sub> = 18 Vdc, V <sub>GG</sub> = 7.0 Vdc, f = 200 MHz) (V <sub>DD</sub> = 24 Vdc, V <sub>GG</sub> = 6.0 Vdc, f = 45 MHz)	NF	—	3.5 4.0	dB

MOTOROLA SMALL-SIGNAL SEMICONDUCTORS

6367254 MOTOROLA SC (XSTRS/R F)

96D 82621 D

3N211, 3N212, 3N213

T-31-25

**ELECTRICAL CHARACTERISTICS** (continued) ( $T_A = 25^\circ\text{C}$  unless otherwise noted.)

Characteristic		Symbol	Min	Max	Unit
Common Source Power Gain ( $V_{DD} = 18\text{ Vdc}$ , $V_{GG} = 7.0\text{ Vdc}$ , $f = 200\text{ MHz}$ ) ( $V_{DD} = 24\text{ Vdc}$ , $V_{GG} = 6.0\text{ Vdc}$ , $f = 45\text{ MHz}$ ) ( $V_{DD} = 24\text{ Vdc}$ , $V_{GG} = 6.0\text{ Vdc}$ , $f = 45\text{ MHz}$ ) ( $V_{DD} = 18\text{ Vdc}$ , $f_{LO} = 245\text{ MHz}$ , $f_{RF} = 200\text{ MHz}$ )	3N211	$G_{ps}$	24	35	dB
	3N211		29	37	
	3N213	$G_C(6)$	27	35	
	3N212		21	28	
Bandwidth ( $V_{DD} = 18\text{ Vdc}$ , $V_{GG} = 7.0\text{ Vdc}$ , $f = 200\text{ MHz}$ ) ( $V_{DD} = 18\text{ Vdc}$ , $f_{LO} = 245\text{ MHz}$ , $f_{RF} = 200\text{ MHz}$ ) ( $V_{DD} = 24\text{ Vdc}$ , $V_{GG} = 6.0\text{ Vdc}$ , $f = 45\text{ MHz}$ )	3N211	BW	5.0	12	MHz
	3N212		4.0	7.0	
	3N211,213		3.5	6.0	
Gain Control Gate-Supply Voltage(5) ( $V_{DD} = 18\text{ Vdc}$ , $\Delta G_{ps} = -30\text{ dB}$ , $f = 200\text{ MHz}$ ) ( $V_{DD} = 24\text{ Vdc}$ , $\Delta G_{ps} = -30\text{ dB}$ , $f = 45\text{ MHz}$ )	3N211	$V_{GG}(GC)$	—	-2.0	Vdc
	2N211,213		—	$\pm 1.0$	

(1) Measured after five seconds of applied voltage.

(2) All gate breakdown voltages are measured while the device is conducting rated gate current. This ensures that the gate-voltage limiting network is functioning properly.

(3) Pulse Test: Pulse Width =  $300\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

(4) This parameter must be measured with bias voltages applied for less than 5 seconds to avoid overheating. The signal is applied to gate 1 with gate 2 at ac ground.

(5)  $\Delta G_{ps}$  is defined as the change in  $G_{ps}$  from the value at  $V_{GG} = 7.0\text{ Volts}$  (3N211) and  $V_{GG} = 6.0\text{ Volts}$  (3N213).(6) Power Gain Conversion. Amplitude at input from local oscillator is adjusted for maximum  $G_C$ .